

- From the system demonstration studies (T. Liu talk):
 - Maximum number of patterns/tower ~ 1.3 M patterns (hybrid 2 GeV)
 - Pattern density ~ 300 k patterns/AM chip $\rightarrow$ 4 AM chips/PRM
 - A fast chip: AM clock ~ 250 MHz
 - Power limit to less than ~ 10 W/chip
 - Pipeline processing of the events:
 - Load events of “next event” N+1 while outputting matched roads of the “current event” N
 - Chips to be operated in a PRM and with 1:1 connection with the FPGA
 - Limits the number of I/O lines to and from the AM chip
- Thanks to the interplay between the AM and the FPGA the requirements are not that strict but leave some level of margins.



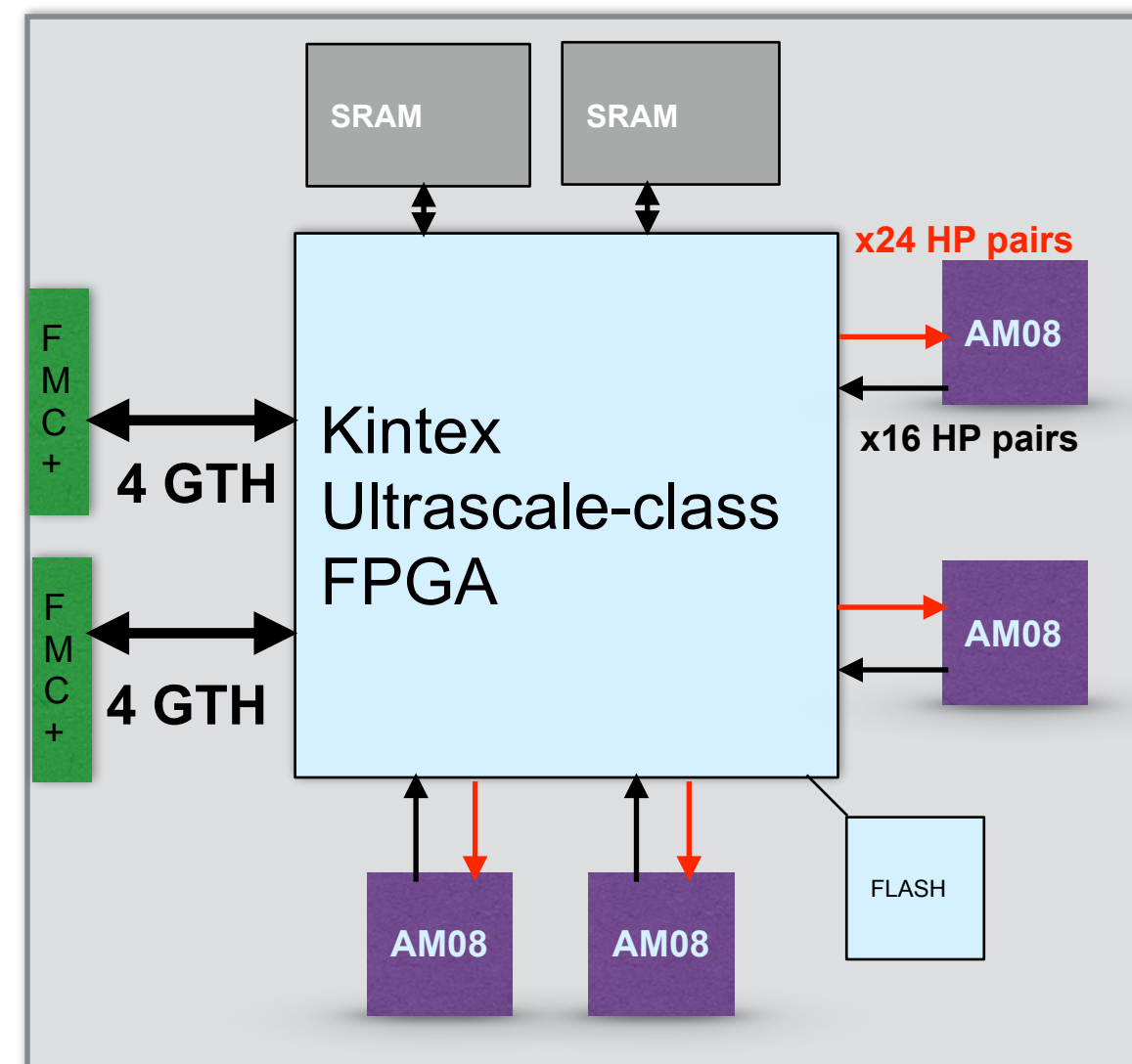
AM08 chip possible design



AM08 chip

-  28 nm technology TSMC - core frequency 250 MHz
-  Pattern density: 0.4-0.5 M Patterns/chip (3-4 times AM06) - but AM08 will be a test chip!
-  8 input buses at 16 bits
 - each bus has 4 HP pairs running at 1.25 Gbps.
 - In CMS only 6 buses are used in the AM - 8 input buses is to remain compatible with ATLAS
-  4 output buses@32 bits (of which 19 for patterns and 8 for bitmap)
 - each bus is has 4 HP I/O pairs running at 1.25 Gbps
-  Every chip will have 32 input HP pairs + 16 output HP pairs, with a total of 96 signal balls
 -  For CMS only 24 input pairs are connected (6 layers only)
-  Power estimate (for full chip)
 - Energy per comparison/bit: extrapolate from KOXORAM ~0.2 fJ/comparison/bit to full chip 0.5 fJ/comparison/bit
 - For 500 k patterns/8 layers@250 MHz, 100% usage: 8 W

- A double FMC PRM08 mezzanine exercise
 - Double FMC^(*) from Pulsar board
 - 2x4 GTH (up to 16 Gbps) - 8 layers
 - Possible to process 120+ Gbps (x10 TM)
 - 4 AM08 chips fed in parallel
 - 4x [24_{IN} (6 layers) + 16_{OUT}] HP pairs
 - up to 1.5-2 M patterns
 - could accommodate 2 GeV thresholds
 - Parallel I/O allows to reduce latency
 - 2 SRAM
 - Power from AM08 ~32 W
 - Power from FPGA+all the rest ~35 W
- Power per ATCA blade due to 2 PRM08 ~150 W
- We have studied a design compatible with 16 AM chips for ATLAS (see backup slides)



*NB: FMC connectors could be for example replaced by SAMTEC SEAM-XX



Plan-B



- **Change minimally AM06**
 - ♦ revise I/O registers and logic
 - replace SER-DES with LVDS
 - replace registers and Fisher tree in the output to accommodate shorter latency (ideally ~10 clock cycles)
 - increase clock frequency to ~200 MHz